

HKMA Launches Digital Bond Grant Scheme

The following is issued on behalf of the Hong Kong Monetary Authority:

The Hong Kong Monetary Authority (HKMA) launched today (November 28) the Digital Bond Grant Scheme (DBGS), which was announced in the 2024 Policy Address.

The DBGS aims to promote the development of the digital securities market and encourage broader adoption of tokenisation technology in capital market transactions. Subject to the satisfaction of relevant eligibility requirements under the DBGS, a maximum grant of HK\$2.5 million will be offered to each eligible digital bond issuance in Hong Kong.

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Following industry consultation, the HKMA has set out the details of the DBGS in the [Guideline on the Digital Bond Grant Scheme](#). The DBGS will start accepting applications today, with an initial period of three years.

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